

# Status of multilayer coatings for EUV Lithography

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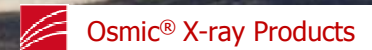
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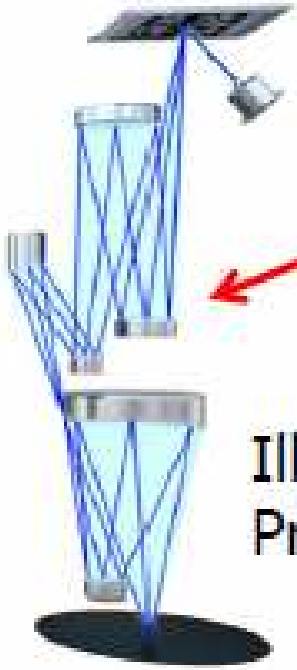
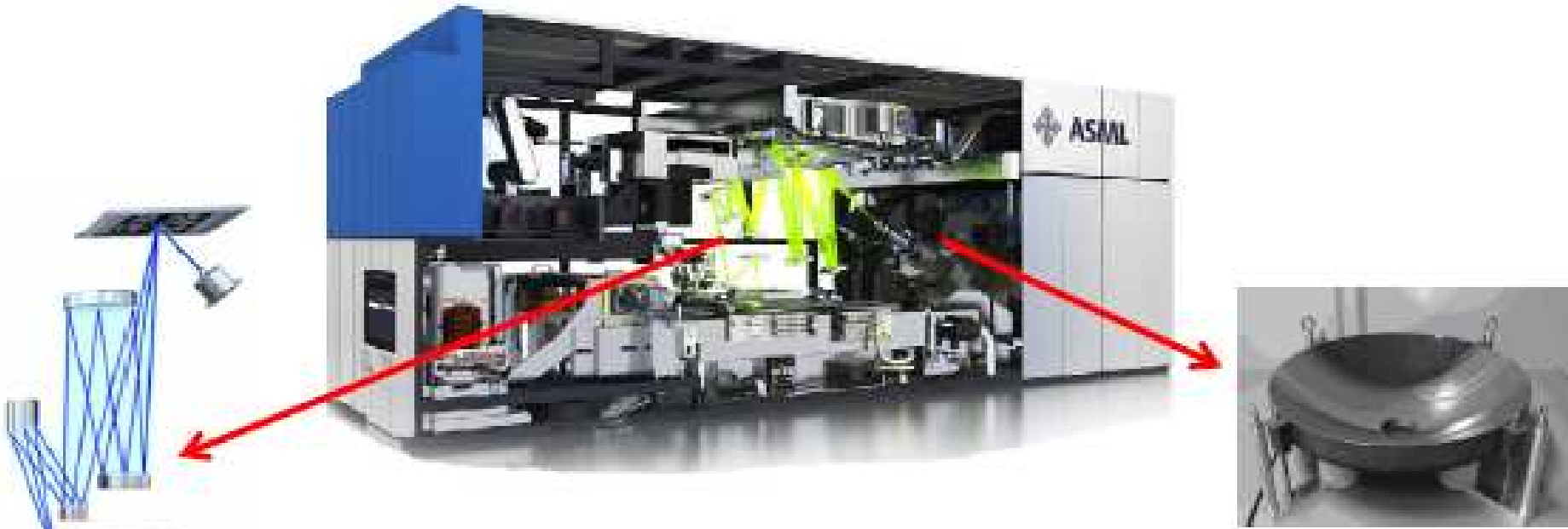
**FOM Institute  
for Plasma Physics  
Rijnhuizen,  
The Netherlands**



## Outline

- Introduction
- Performance versus Specifications
- Best ML performance
- ML stability
- ML coatings infrastructure
- ML for Next Generation EUVL
- Multilayer technology readiness for HVM
- Conclusion

# ASML NXE Scanner Requires 11+ ML Optics



Illuminator and Projection optics



High Power Source Collector optic

+ ML on mask blanks

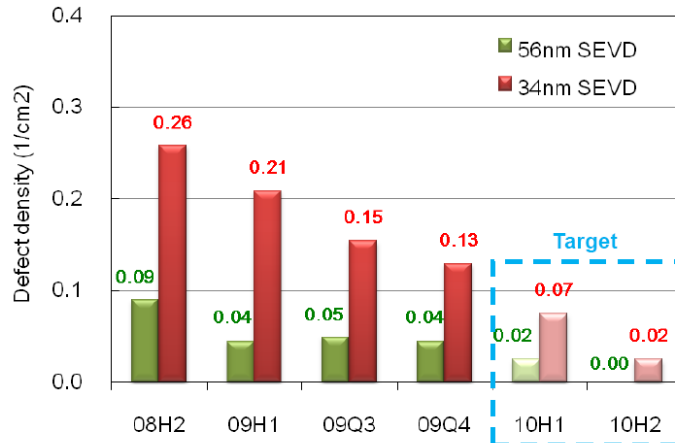
# Is today's ML deposition technology ready for HVM?

- ML performance versus specification
- ML parameters to improve
  - Feasibility for improvement
- Infrastructure and capacity
  - Deposition facilities
  - Metrology
  - Substrates suppliers

# Defects in mask blanks

Innovative Technologies

Best defect trend of LTEM-ML blank  
(Lasertec M1350A inspection)



Asahi Glass: 2010 Maui Workshop

## Structure

CrN/LTEM/ML/Ru

## CTE of LTEM

Mean CTE -3.5 ppb/K  
CTE variation (PV) 1.7 ppb/K

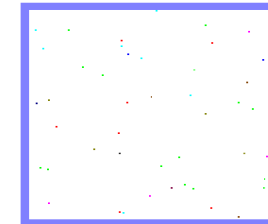
## Substrate flatness

front 89 nm  
back 76 nm  
Blank Flatness(Bow) 0.38 μm

## Reflectivity

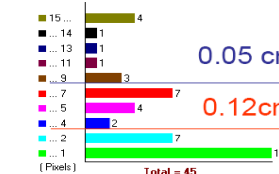
Peak R 66.2 %  
R range(Abs.) 0.3 %  
centroid λ 13.535 nm  
λ range 0.026 nm

Defect map and histogram



"Look Beyond"  
**AGC**

Pixel Histogram



0.05 cm<sup>-2</sup> @ >56nm SEVD

0.12cm<sup>-2</sup> @ >34nm SEVD

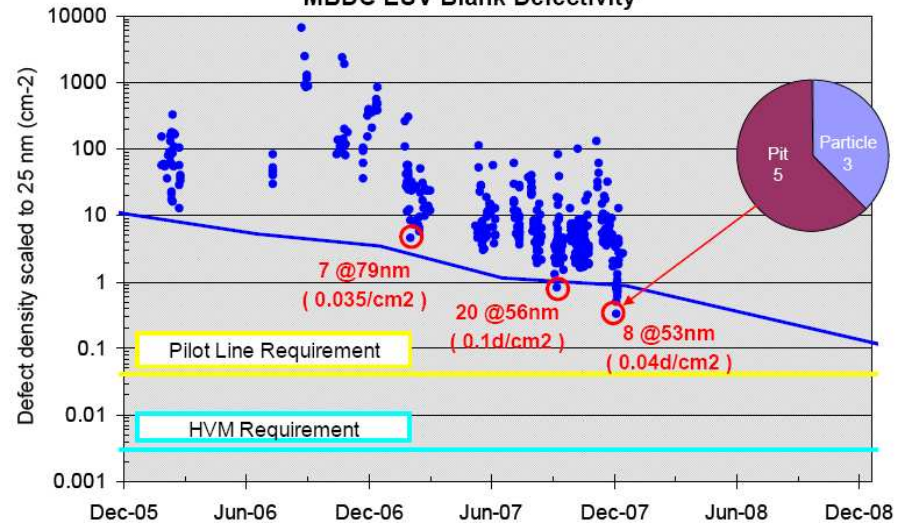
Asahi Glass: 2010 Maui Workshop

Sungmin, et al, (Samsung Electronics) in  
Proc. SPIE Vol. 7969 (2011)



"Pit defects are the most dominant, accounting for on average 75% of defects observed. ... The remaining 25% of the defects are due to particles deposited during the deposition process."

MBDC EUV Blank Defectivity



P. Kearney, et al., "Ion beam deposition for defect-free EUVL mask blanks," Proc. SPIE 6921, 69211X (2008)

presented by O. Wood: 2010 Maui Workshop



Maui EUVL Workshop, 14-17 June 2011

# Collector for NXE3100

Multilayer optics for EUV and beyond

$\lambda = 13.5 \text{ nm}$

## LPP collector coating challenges

$R > 65 \%$

$\lambda = (13.500 \pm 0.050) \text{ nm}$

→  $\Delta d = 0.025 \text{ nm} = 25 \text{ pm}$

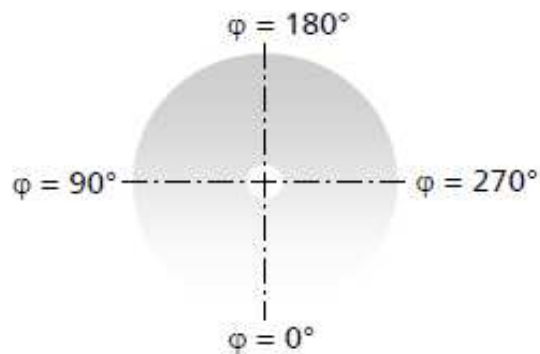
- Diameter: > 660 mm
- Lens sag: > 150 mm
- Tilt: > 45 deg
- Weight: > 40 kg





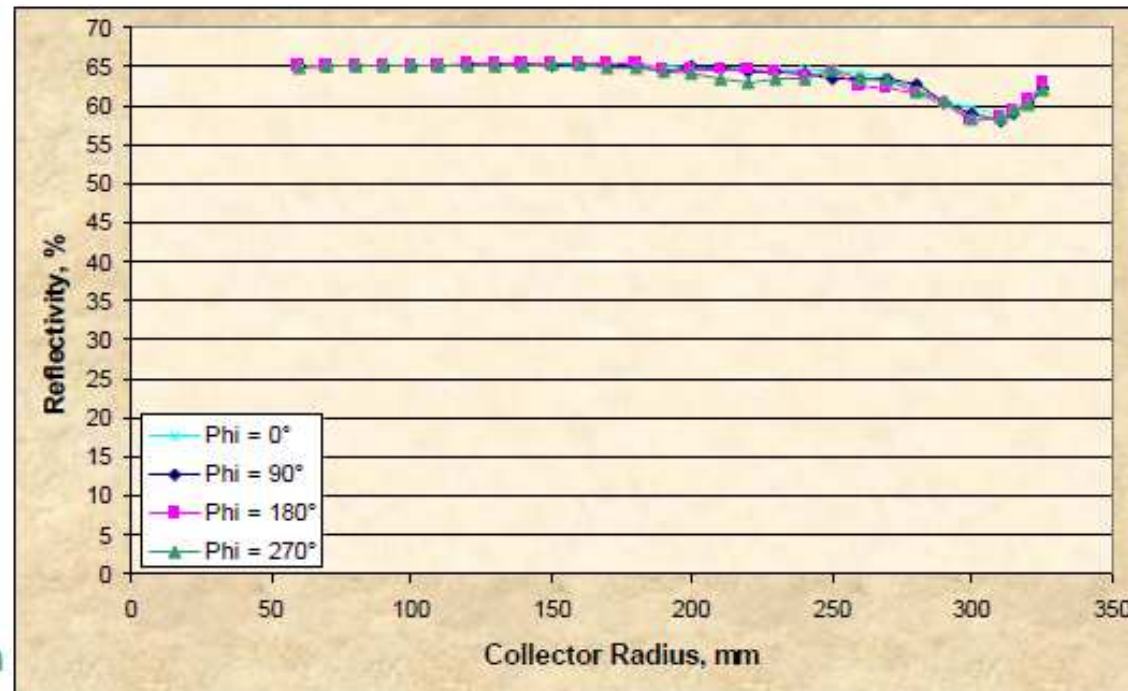
# Reflectivity radial uniformity

Reflectivity of LPP collector mirror



Maximum reflectance along four lines within clear aperture of collector mirror:

$R \sim 65\% @ r < 240 \text{ mm}$   
 $R \sim 59\% @ r = 250 \dots 320 \text{ mm}$

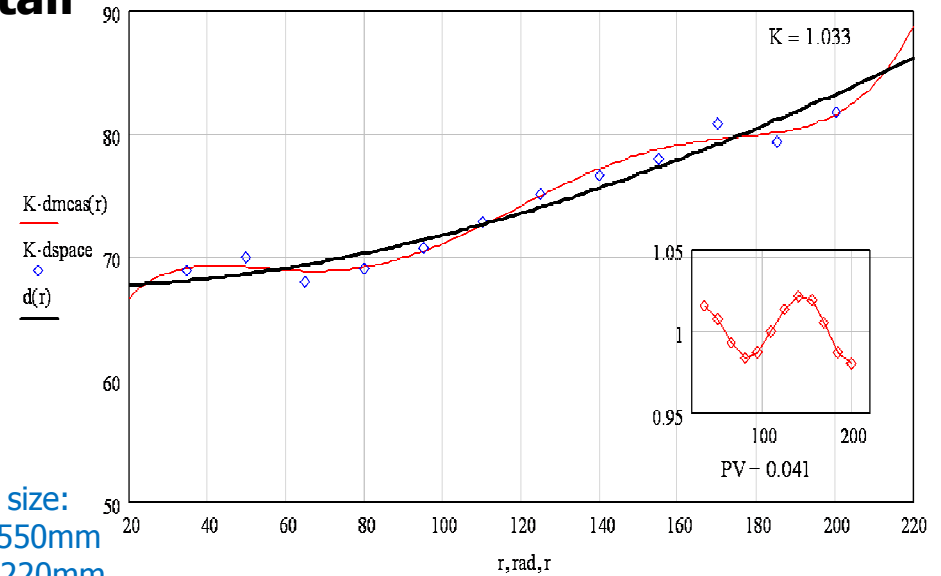
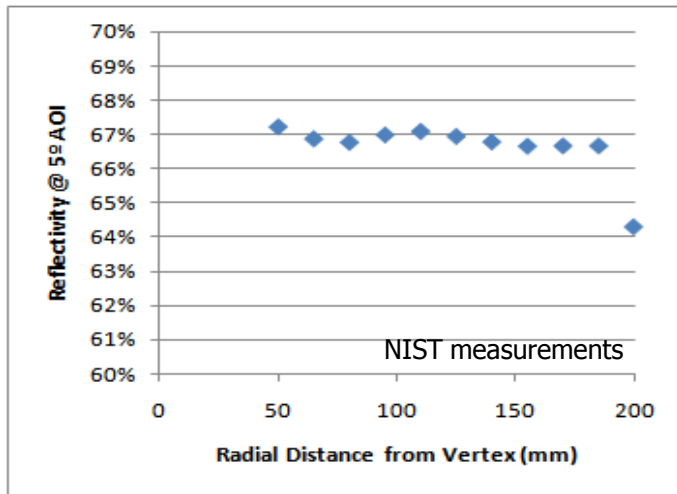


Measurements: PTB Berlin



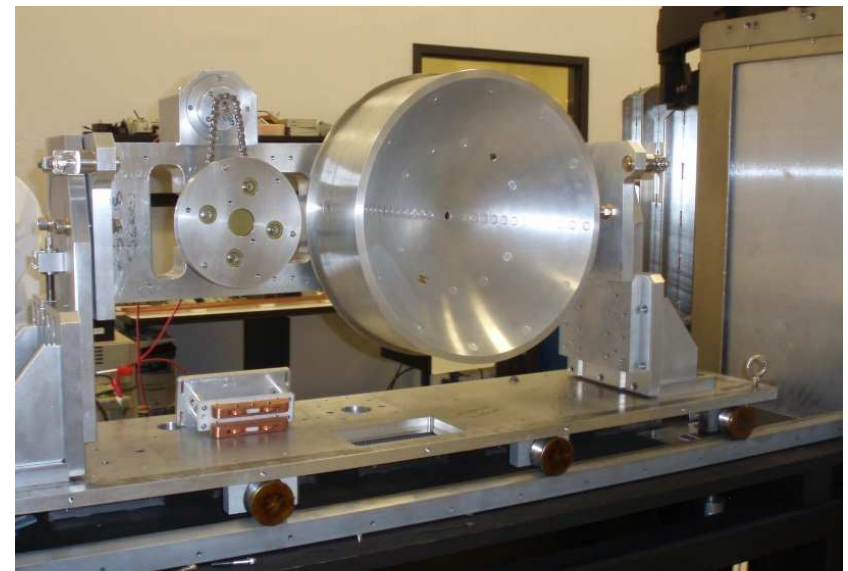
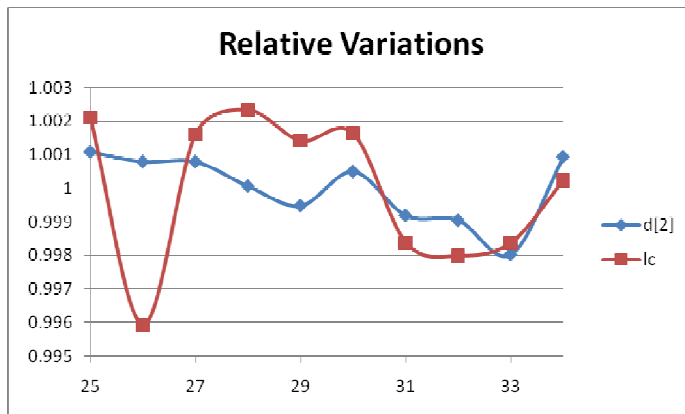
# Collector optics deposition at RIT Innovative Technologies

## Preliminary results: 3 weeks after install



Maximum size:  
Diameter – 550mm  
Thickness – 220mm

median  $\lambda_c$  ranged 13.77 @ 50mm to 13.33nm @ 200mm  
total height range (sag) is 97mm  
angle of surface is 13° - 49°





# Illuminator: Reflectivity 1

## Illuminator optics Alpha Demo tool

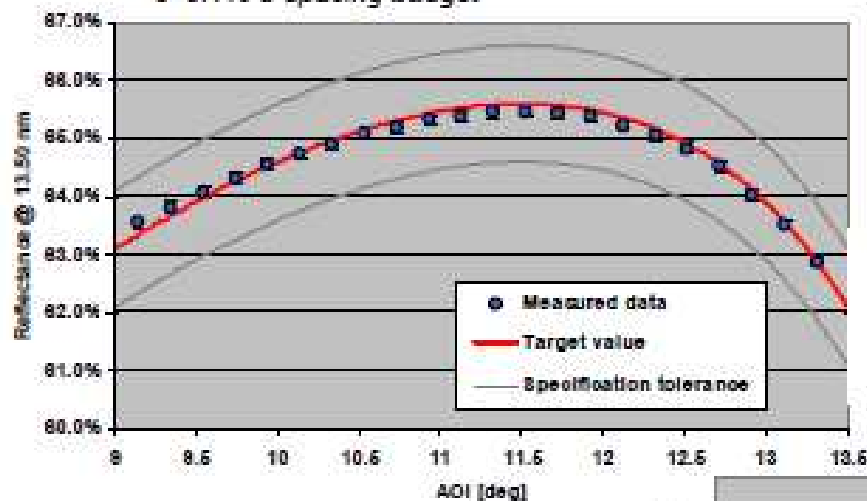
Highly convex illuminator element

Reqd. reflectivity @ used AoI +/- 1% of target value

→ 0.1% d-spacing budget



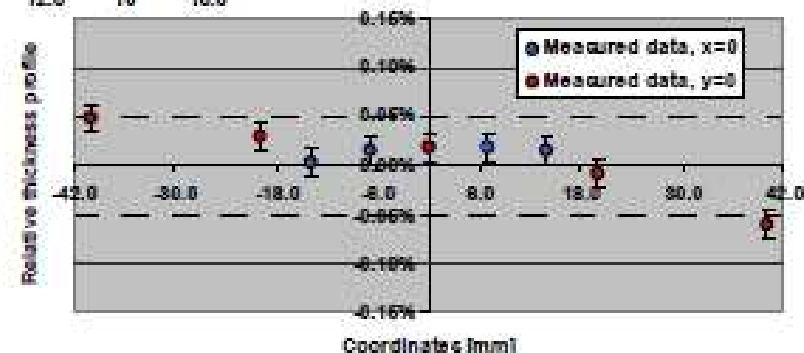
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Rijnhuizen,  
The Netherlands



### Results deposition

- d-spacing within +/- 0.05%
- Lateral reflectivity uniformity +/- <0.5% of target value @ used AoI
- ✓ Factor 2 within specification

(2005)



# Illuminator: Reflectivity 2

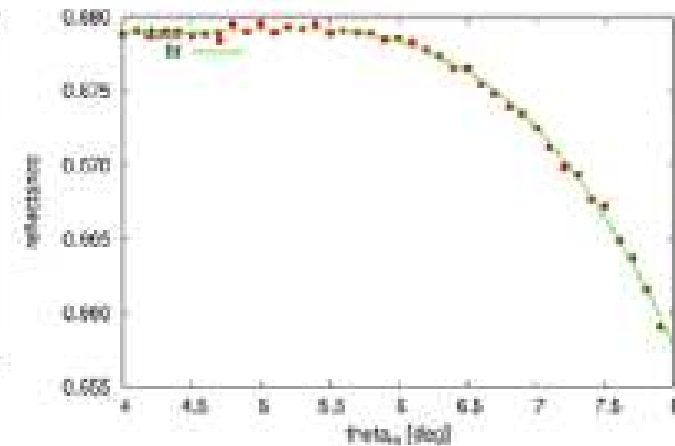
*Illuminator optics Alpha Demo tool*

**ZEISS**

**Carl Zeiss SMT GmbH**  
Oberkochen  
Germany



480 mm



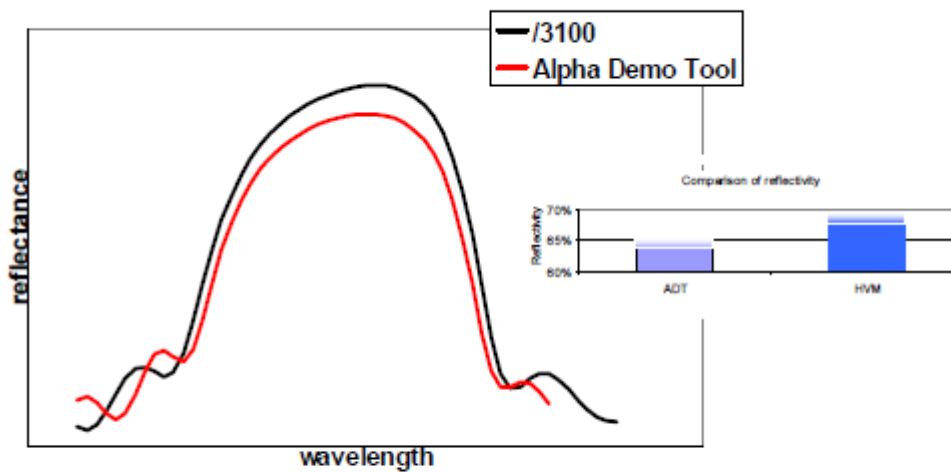
**Largest EUV ML optic to date successfully coated**

- First real EUV optic from new large area EUV coating facility @ Zeiss
- Several new coating technologies successfully incorporated
- Lateral uniformity < 0.2%: within spec (0.3%)
- Reflectivity 67% (EUVR characterized)

(2005)

# Projection optics: towards to HVM

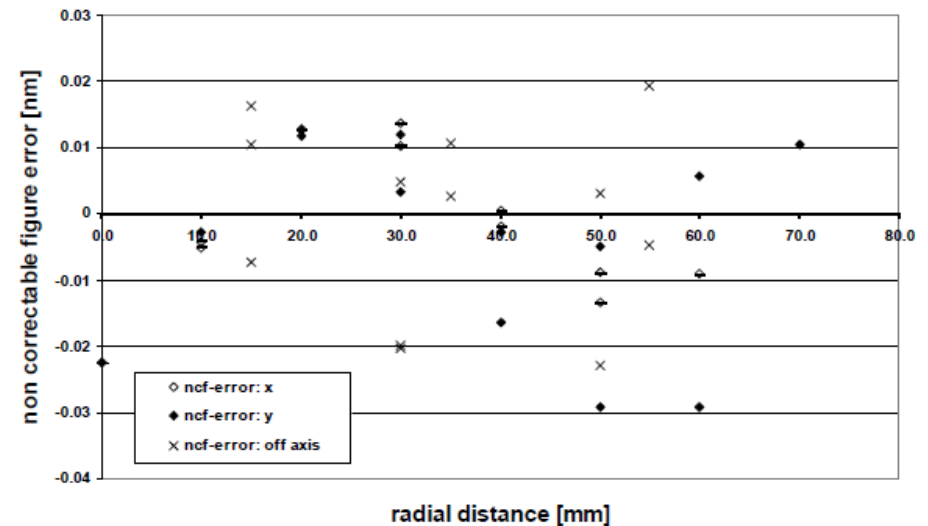
## Improvement since ADT



→ 69.7% Reflectance at local angle of incidence

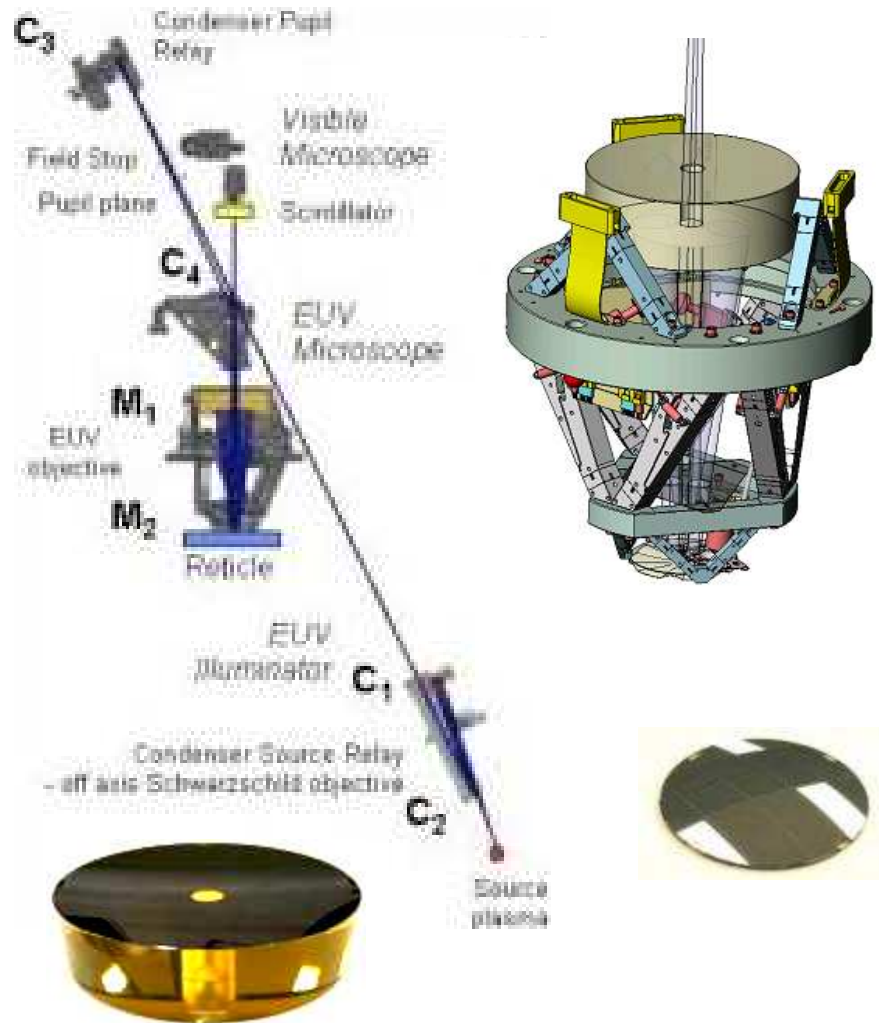
→ ~50% higher transmission of the PO-BOX

## Non correctable added figure error

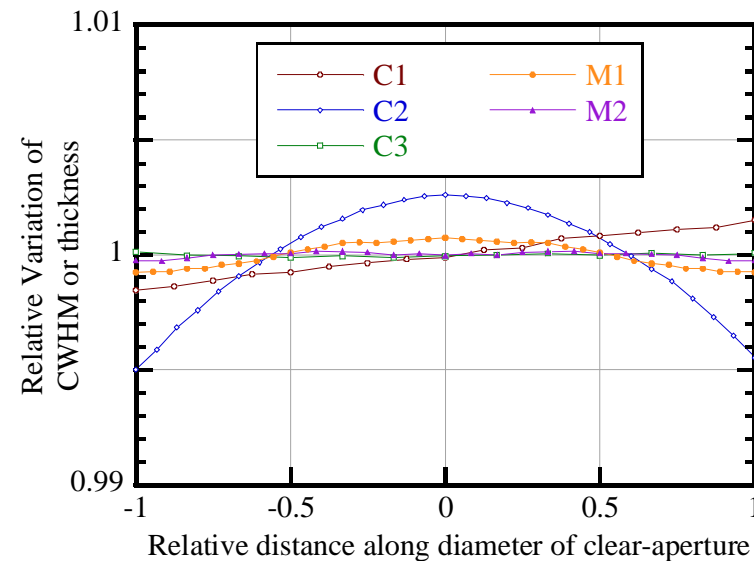


Coating added figure error less then 35 pm  
Spec is 100 pm

# Reticle Imaging Microscope (RIM, 2005)



- 4 condenser (1 Ru, 3MoSi)
- 2 imaging (MoSi)
- Added Figure Error in imaging optics:
  - M1: 0.015nm
  - M2: <0.010nm



H.Glatzel et al. Characterization of prototype optical surfaces and coatings for the EUV Reticle Imaging Microscope, Proc. of SPIE, Vol. 5751 (2005), 1162 – 1169.

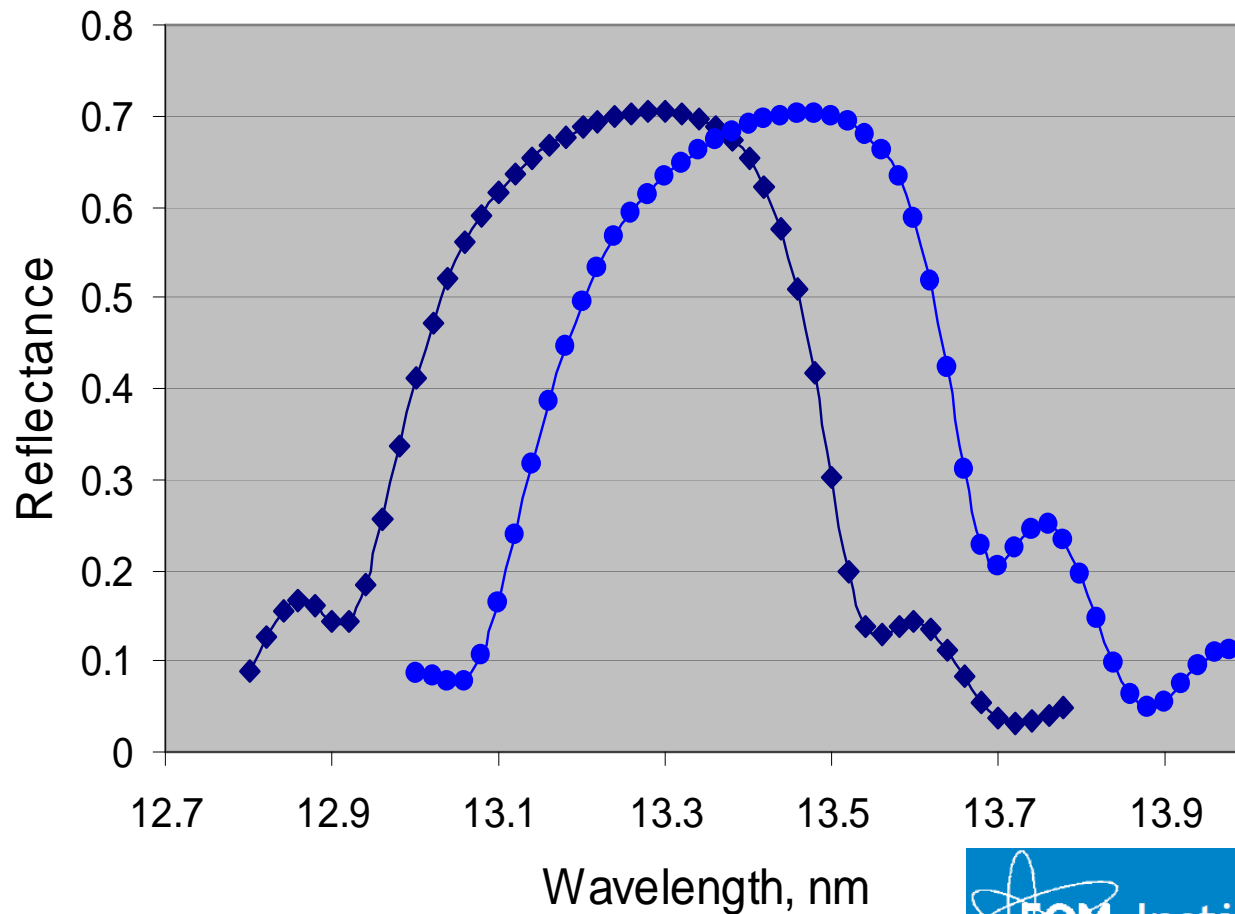
# Spec and achieved performance

Application	Parameter	$\lambda_c$ , nm	$\Delta\lambda_c$ , nm	Rp, %	$\Delta Rp$ , %	Stress, MPa	Defects, cm <sup>-2</sup>	Figure Error, nm rms
Mask blanks	Spec	$\pm 0.030$ (i)	$\pm 0.025$ (i)	$\geq 67$ (a)	$\pm 0.025$ (a)	200 (a)	$< 0.003$ (a)	
	Achieved	$\pm 0.006$ (b)	$\pm 0.010$ (b)	67.1 (c)	$\pm 0.025$ (b)	200-400 (b)	0.05 at 56nm (c)	
Collector	Spec		$\pm 0.05$ (j)					
	Achieved	$\pm 0.020$ (j)	$\pm 0.015$ (j)	65 (j)	$\pm 5$ (j)			
Illuminator	Spec		$\pm 0.014$	$\geq 67$ (f)	$\pm 1$ (g)	100 (a)		
	Achieved	$\pm 0.010$ (d)	$\pm 0.014$ (e)	69.1(f)	$\pm 0.2$ (g)	35 (f)		
Projection optics	Spec			$\geq 67$ (f)	$\pm 1.0$ (g)			0.0014 (f)
	Achieved	$\pm 0.010$ (d)	$\pm 0.008$ (d)	69.1(f)	$\pm 0.02$ (g)	35 (f)		0.0002 (f)



# Best ML performance

**70.5% @ 13.3 nm** **70.15% @ 13.5 nm**

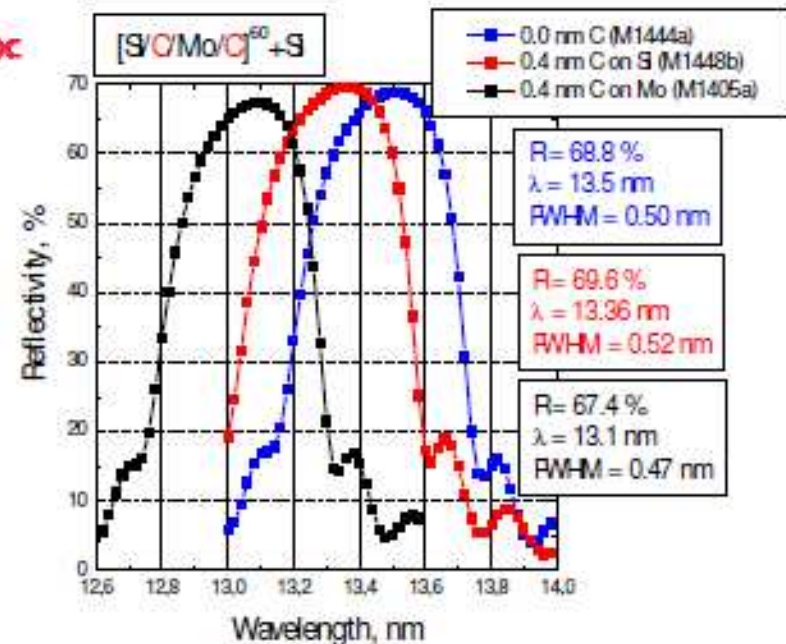
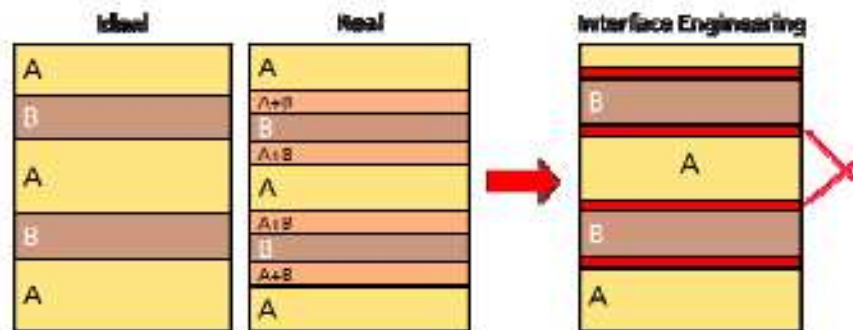


- *data PTB, Berlin*
- *1.5 degrees off-normal*
- *Diffusion barrier X at both interfaces*

Multilayer optics for EUV and beyond

$\lambda = 13.5 \text{ nm}$

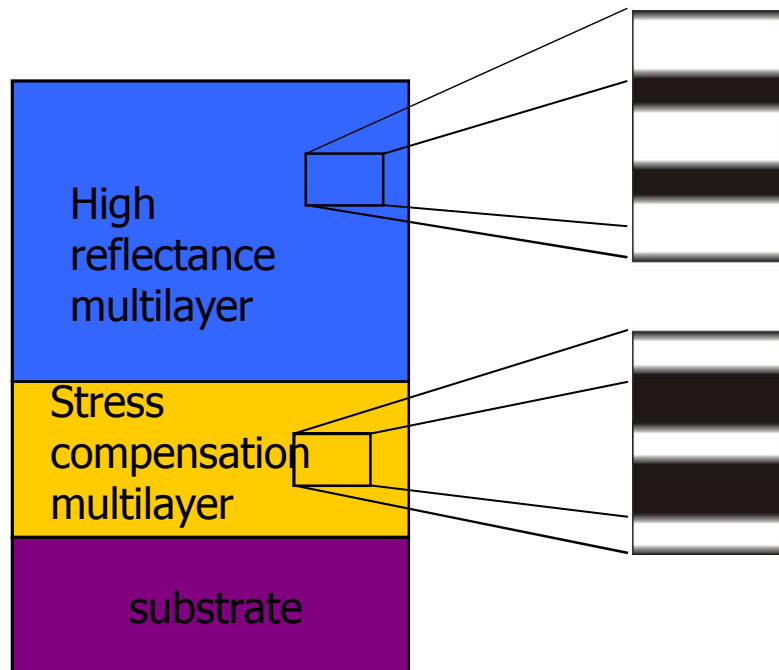
## Enhancement of Reflectivity by Interface Engineering



- Optimized Design: [Mo/Si/C]
- R (without C) = 68.8 %
- R (with C on Si) = 69.6 %

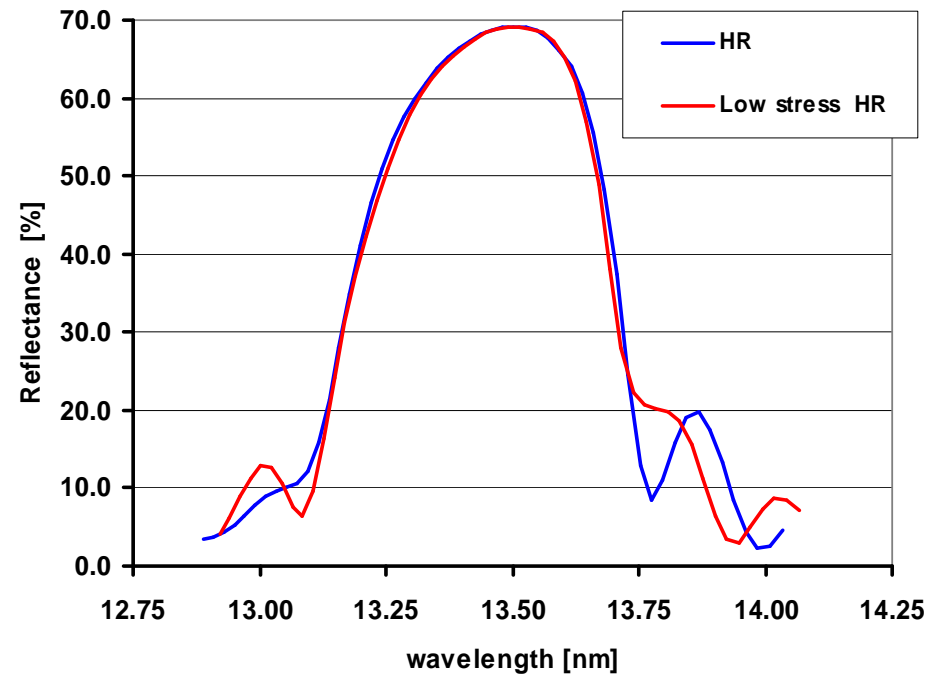
+ 0.8%

S. Yulin et al., "interface-engineered EUV multilayer mirrors", MEE 93, 2006



P.B. Mirkarimi et al, Opt. Eng. 38, 1999

▪ *-200 MPa reduced to -30 MPa*



- *Stress compensation*
- *No effect on reflectance*  
*Erwin Zoethout et al, SPIE 5037, 2003*

# ML stability

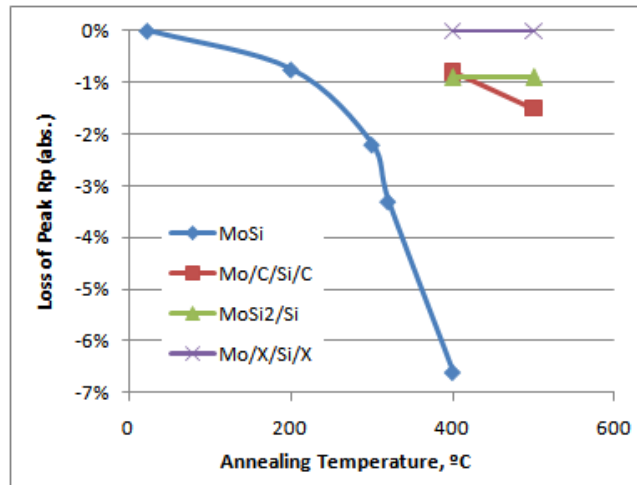
- Temperature stability
  - Barrier layers
- Radiation stability
  - Capping layer



# Temperature stability

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## Reflectivity

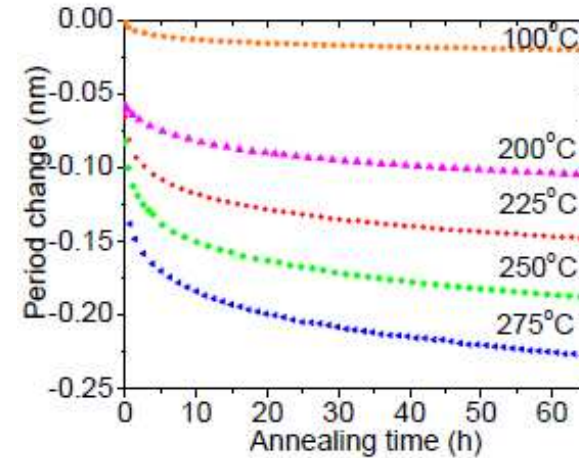


System	Temperature range	R <sub>13.5 nm</sub> %	FWHM, nm
MoSi <sub>2</sub> /Si	≤ 500°C	41.2	0.26
Mo/C/Si/C	≤ 250°C	59.6	0.54
Mo/X <sub>1</sub> /Si/X <sub>1</sub>	≤ 400°C	60.0	0.49
Mo/X <sub>2</sub> /Si/X <sub>2</sub>	≤ 500°C	58.8	0.50

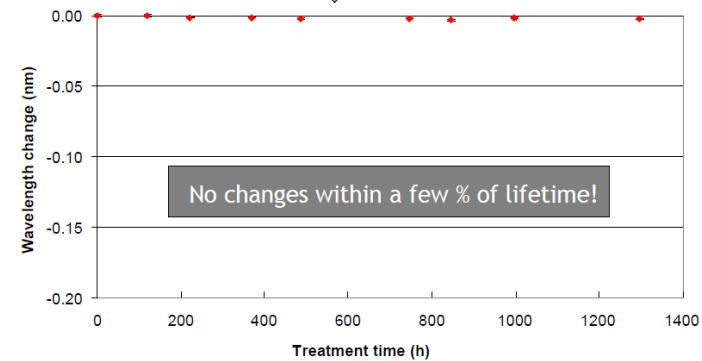
Mo/Si taken from: C. Montcalm, Eng. Opt. 40, 469 (2001)  
others from: S. Yulin, SPIE 5751, 1155 (2005)



## Period



Solution: ***Barrier stabilization***



## High reflectance multilayers of EUVL HVM-projection optics

E.D. van Hattum<sup>1</sup>, S. Alonso van der Westen<sup>1</sup>, P. Salló<sup>1</sup>, K.T. Grootkarzijn<sup>1</sup>, E. Zoethout<sup>1</sup>, R. van de Kruijjs<sup>1</sup>, E. Louis<sup>1</sup>, S. Bruijn<sup>1</sup>, J. Bosgra<sup>1</sup>, A. Yakshin<sup>1</sup>, G. von Blanckenhagen<sup>2</sup>, H. Enkisch<sup>2</sup>, S. Müllender<sup>2</sup>, and F. Bijkerk<sup>1,3</sup>

Maui EUVL Workshop, 14-17 June 2011 San Jose, 2010

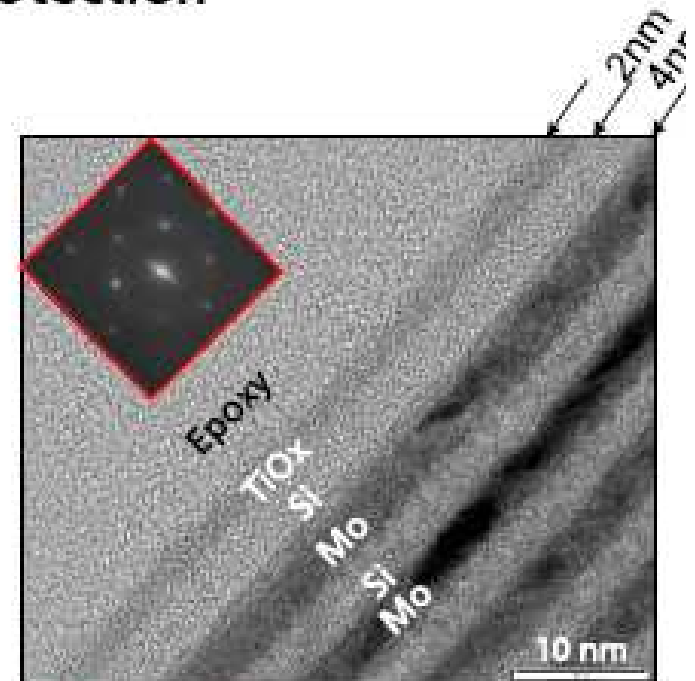
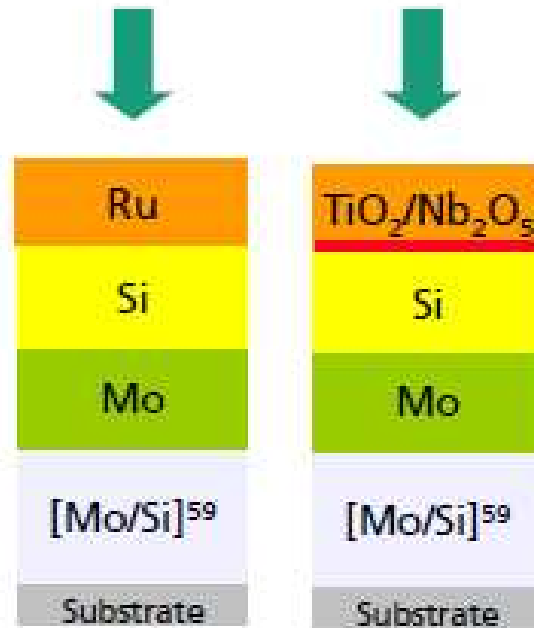
## Capping layers for EUV lithography optics protection

### Three conceptions:

- Nobel metals (Ru, Au, Pt, Pd)
- Stable oxides (RuO<sub>2</sub>, TiO<sub>2</sub>, Nb<sub>2</sub>O<sub>5</sub>)
- Multilayer conception

1999-2005

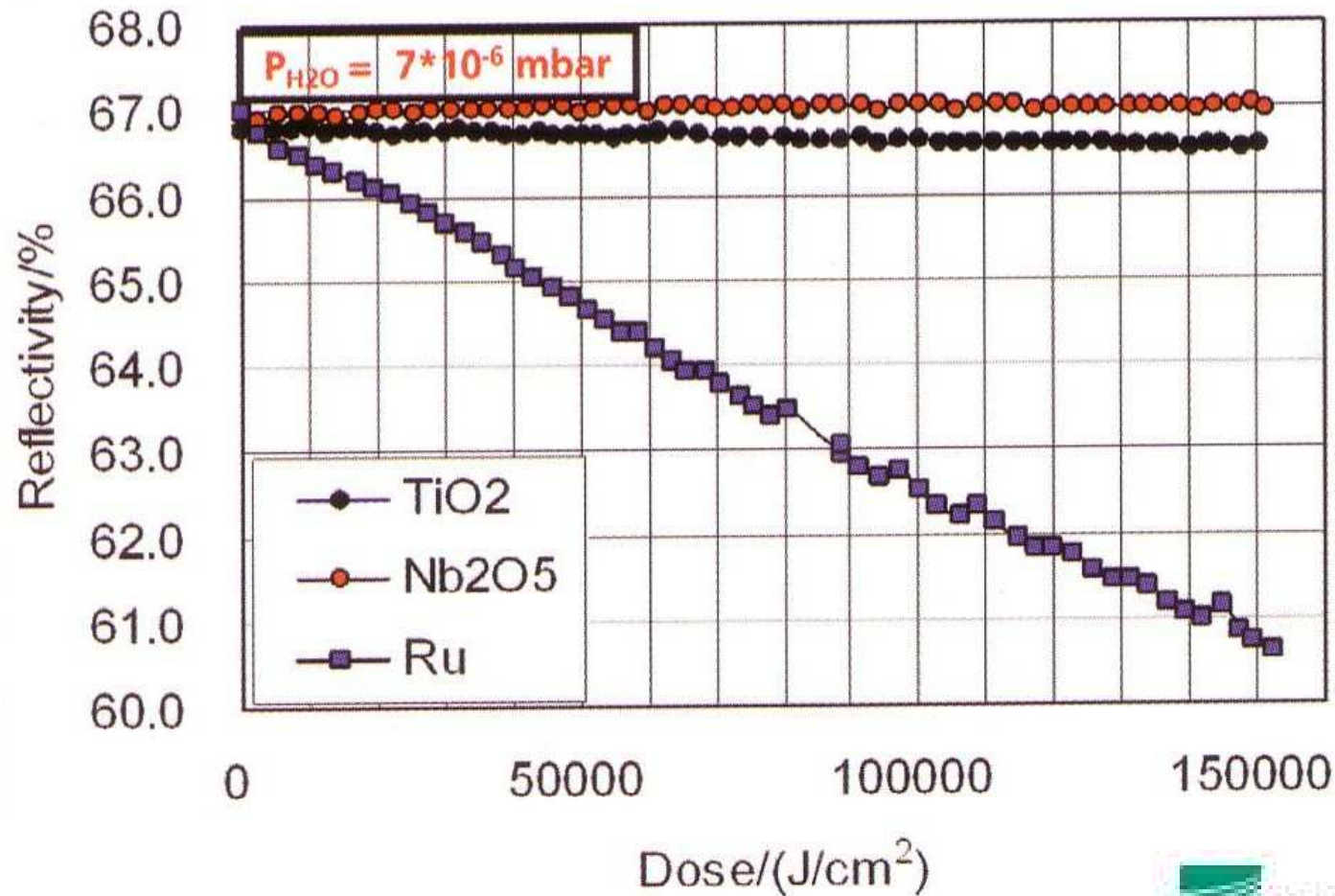
2005-2010



- Chemically inert to oxygen
- Good optical properties
- Amorphous structure
- Photo catalytic properties

# Radiation stability

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 **Fraunhofer**  
IOF

 **Rigaku**

Maui EUVL Workshop, 14-17 June 2011

# Infrastructure

- Deposition facilities
- ML Performance Metrology
- Substrates

# ML deposition facilities



**ZEISS**

**Carl Zeiss SMT GmbH**

Ostalb, Region Ost-Württemberg, Baden-Württemberg  
Rudolf-Eber-Str. 2  
73447 Oberkochen  
Germany



**ZEISS**

## EUVL multilayer coating development

E. Louis, E. Zoethout, R.W.E. van de Kruijs, I. Nedelcu, A.E. Yakshin,

S. Alonso van der Westen, T. Tsarfati, and F. Bijkerk

*FOM Institute for Plasma Physics Rijnhuizen, the Netherlands*

H. Enkisch, G. Sipos, S. Müllender, and P. Kürz

*Carl Zeiss SMT AG, Oberkochen, Germany*

(San Jose, 2005)

### ***EUV application specific coating facility***

- Based on 'FOM coating process'
- Allows deposition of >500 mm optical diameters
- UHV conditions ( $4 \times 10^{-9}$  mbar)
- New ways of layer plasma treatment
- Improved layer thickness control (x-ray monitoring)
- Reflectance at 13.5 nm 67%
- Wavelength matching PV 0.15%
- Lateral uniformity of periodicity PV 0.12%



Van Loyen et al, SPIE Sta Clara (2003) ML5038-3



### ***On-site EUV reflectometer***

- Up to 500 mm dia, 30 kg samples
- Reproducibility reflectance 0.5%, wavelength 0.01%





# FOM Institute for Plasma Physics Rijnhuizen, The Netherlands



Demounting of a batch of multilayer test samples  
in one of the nSI UHV deposition systems  
(photo by N. Steenkamp)



## Deposition equipment



Analysis equipment: High resolution, in-vacuum XPS, AES, SEM and STM







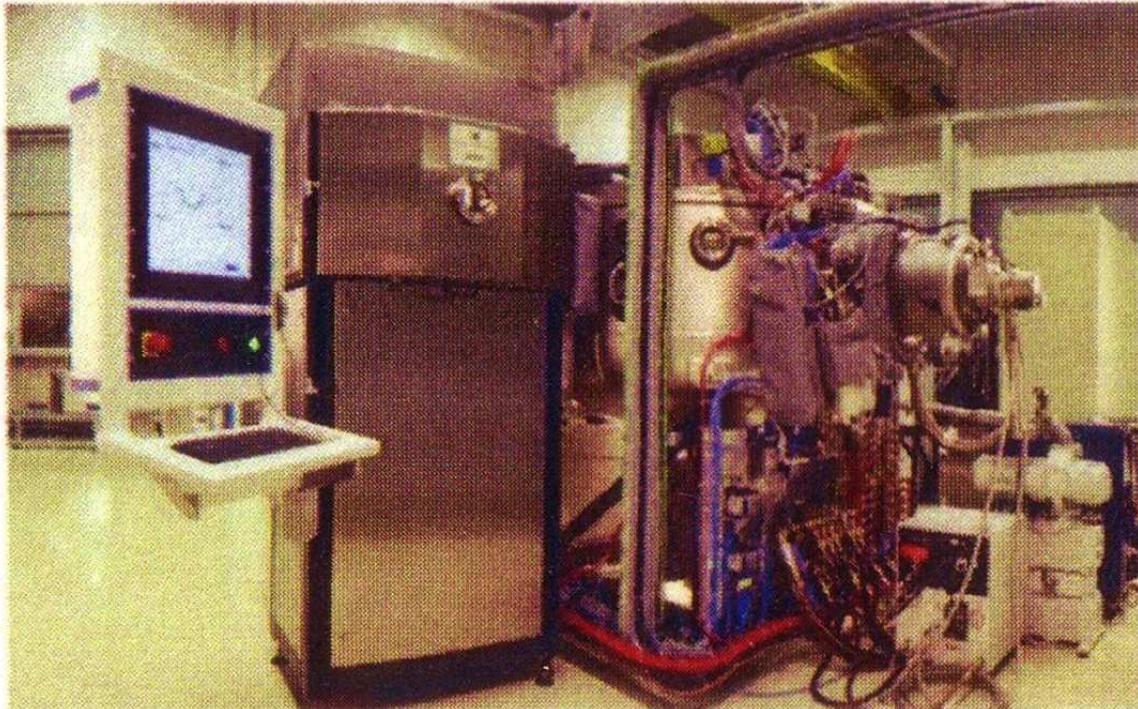
# Fraunhofer

## IOF



# Multilayer deposition

Sputtering system NESSY-1



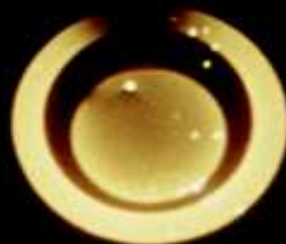
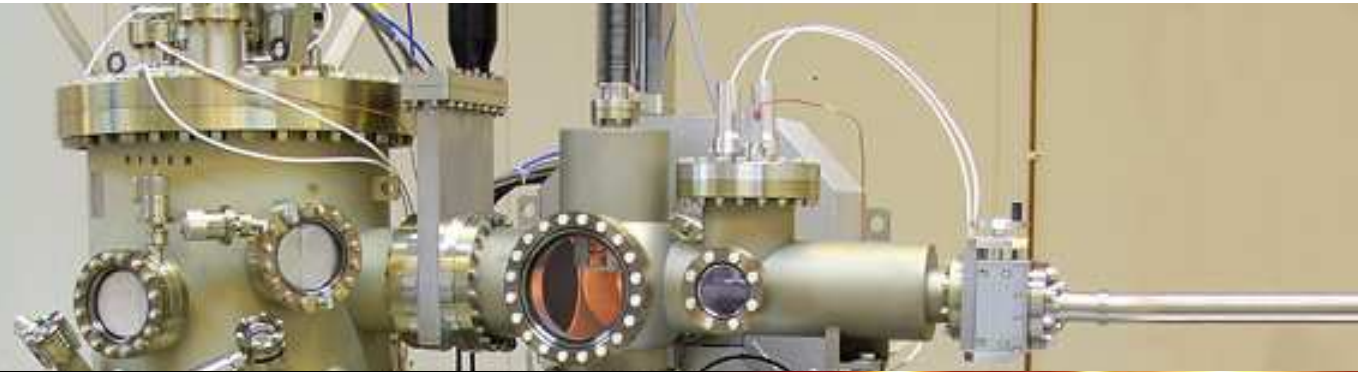
## Sputtering system Nessy 1

- base pressure:  $1 \cdot 10^{-9}$  Torr
- work pressure: 0.2 – 0.8 mTorr
- sample size:  $D < 650$  mm
- 4- magnetrons dif. Barriers
  
- Thickness uniformity 0.2% on 300 mm
- Reflectivity uniformity  $\pm 0.3$  % (Mo/Si)
- Thickness gradient  $\pm 50$ % on 300 mm
- Load / unload system





# Institute for Physics of Microstructures Russian Academy of Sciences



**IPM**  
**Nizhniy Novgorod**  
**Russia**

Maui EUVL Workshop, 14-17 June 2011





❑ Multilayer structures (technology; characterization)



Facility providing deposition of 6 different materials in one multilayer structure



Technological stand for deposition of MLSs by means of magnetron and ion-beam sputtering. It allows low energy ion polishing of each layer border and ion-beam assistant deposition

Maui EUVL Workshop, 14-17 June 2011



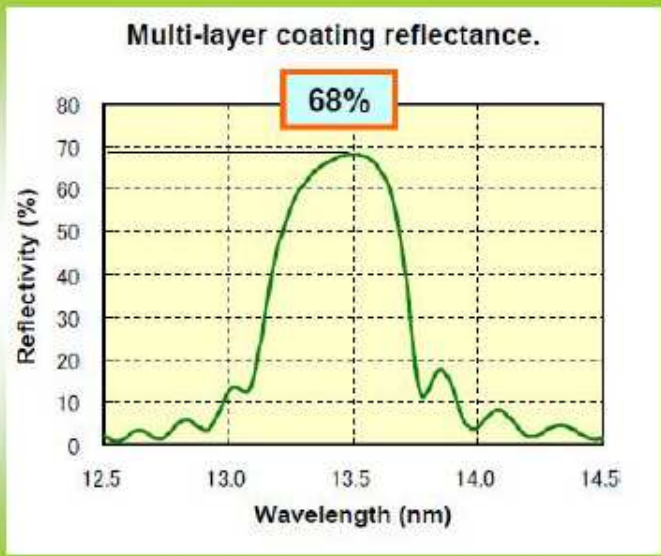
Reflectometer for reflectivity and transparency characterization of XEUV optics in a spectral range of 0.6 – 20 nm



Mirror fabrication technology

Further improvement of MSFR, HSFR  
 ⇒ Lower flare, Higher reflectivity

	MSFR (pmRMS)	HSFR (pmRMS)
PO#1	100~140	70~130
PO#2	70~130	70~120
2010	51	50

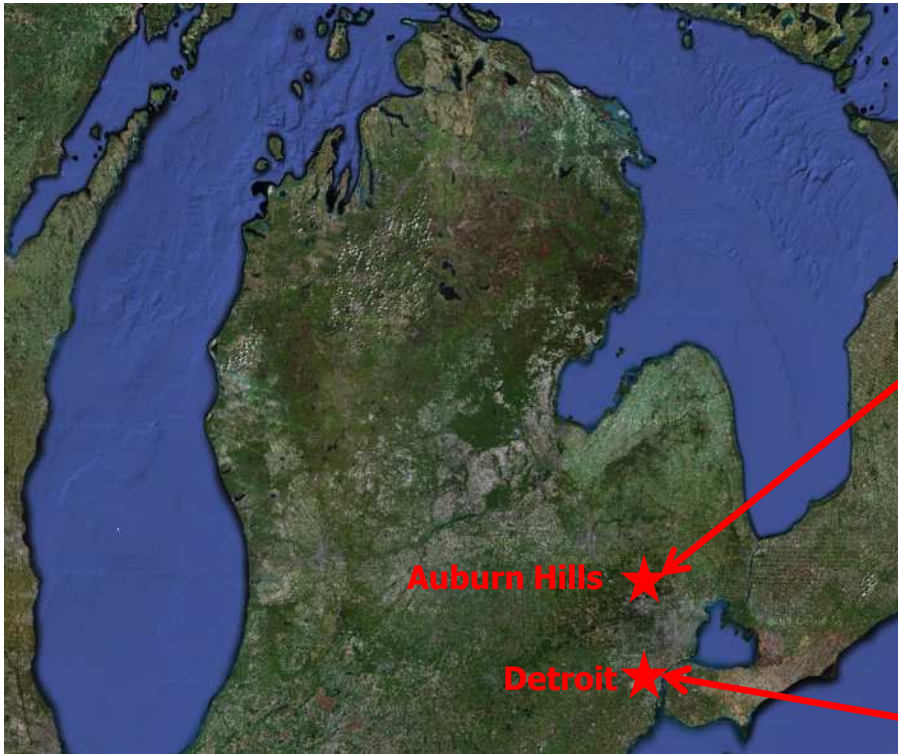


Nikon's optics fabrication technology can meet EUV HVM requirements.





# RIT in Auburn Hills, Michigan



RIT Facility

18 hole golf course



- **Inline Magnetron**
- **7 Carousel Magnetrons**
- **Ion Beam**
- **Class100 cleanroom with class 10 miniroom**
  - Load-locked
  - 5 planar magnetrons
  - 4 process gases
  - 500 x 1500mm carrier
  - 0.2mm accuracy



### • **Wavelength Range**

$$\lambda = 0.2\text{\AA} - 300\text{\AA}$$
$$E = 40\text{eV} - 60\text{keV}$$

### • **Multilayer Period**

$$d_{\min} = 10\text{\AA}$$

### • **Number of Period**

$$N_{\max} = 1000$$

### • **Spectral Resolution**

$$\Delta\lambda/\lambda = 0.2\% \text{ (high-selective)}$$
$$20\% \text{ (depth-graded)}$$

### • **Size:**

~3mm to 1.5 meter

### • **Materials**

W/Si, W/C, Ni/Ti, Ni/B<sub>4</sub>C, Ni/C, Cr/C, Cr/Sc, Mo/Si, Mo/B<sub>4</sub>C, La/B, V/C, Ru/B<sub>4</sub>C, Al<sub>2</sub>O<sub>3</sub>/B<sub>4</sub>C, SiC/Si, Si/C, SiC/C, Fe/Si, Cr/B<sub>4</sub>C, Si/B<sub>4</sub>C, W/Mg<sub>2</sub>Si, V/B<sub>4</sub>C, Ti/B<sub>4</sub>C, etc.

### • **Design**

Uniform or Graded: lateral, radial, bilateral (2D)  
Depth Graded: supermirror & high-selective  
Flat or Curved  
Glancing (<1°) to Normal

# ML reflectivity metrology

# Optics Reflectometry @ 13.5nm

- **Gullikson (CXRO) paper in SPIE 4343 (2001).** (Dmax~200mm, L~400mm)
 

$\lambda_c$ precision: 0.01%	$\lambda_c$ accuracy: 0.03%
Rp precision: 0.12%	Rp accuracy: 0.50%
- **S.Grantham (NIST) (2011).** (Dmax~450mm)
  - median lambda uncertainty:  $\pm 0.10\%$  ( $2\sigma$ ) of the median
  - peak reflectivity uncertainty:  $\pm 0.25\%$  ( $2\sigma$ ) absolute
- **F. Scholze (PTB) paper in SPIE 5751, 749 (2005).** (Dmax >660mm)
  - $\lambda_c$ : 0.0075% week-to-week accuracy; Rp:  $\pm 0.1\%$  rms
  - reproducibility:  $\lambda_c = \pm 0.0008\text{nm}$   $1\sigma$  or  $\pm 0.006\%$   $1\sigma$ , Rp =  $\pm 0.11\%$   $1\sigma$
- **New Subaru (2010).** (Dmax~200mm)
  - $\lambda_c$ : 0.004nm, R: 0.05%, fwhm: 0.001nm
- **Zeiss (2005).** (Dmax~500mm)
- **International Intercomparison (2003?)**
  - $\lambda_c$ : 0.03% agreement b/w CXRO/PTB; 0.029% b/w CXRO/New Subaru
  - Rp: 0.13% agreement b/w CXRO/PTB; 0.05% b/w CXRO/New Subaru



# Multilayers for next generation EUVL at 6.7nm



# Next generation EUVL

Innovative Technologies

EUV and BEUV product roadmap spans >10 years

Next Generation EUVL

	0.25 NA		0.32 NA			Under study >0.40 NA	
	Lens mirrors	6M	6M	6M	6M	6M	6/8M
Wavelength	13.5 nm	13.5 nm	13.5 nm	13.5 nm	13.5 nm	13.5 nm	New $\lambda$
Product	ADT	3100	3300B	3300C	3300D	3500	>3500
Introduction year	2006	2010	2012	2013	2014	2016	>2018
Resolution (hp)	32 nm	27 nm	22 nm	18 nm	16 nm	11 nm	<8 nm
Sigma	0.5	0.8	0.2-0.9	OAI	flex OAI	flex OAI	flex OAI
Overlay (SMO)	7.0 nm	4.5 nm	3.5 nm	3.0 nm	2.5 nm		
Throughput (wph)	4 wph	60 wph	125 wph	150 wph	180 wph		
Dose (mJ/cm <sup>2</sup> )	5	10	15	15	15		
Source (W)	3	105	250	350	500		

EUV Source Workshop, Dublin, Nov 2010

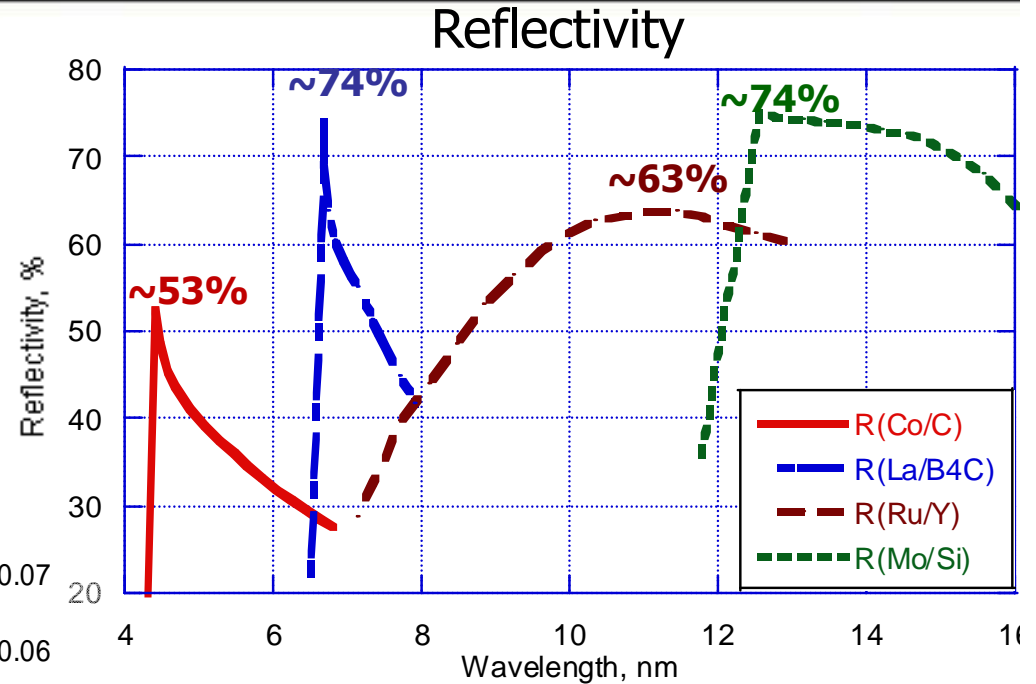
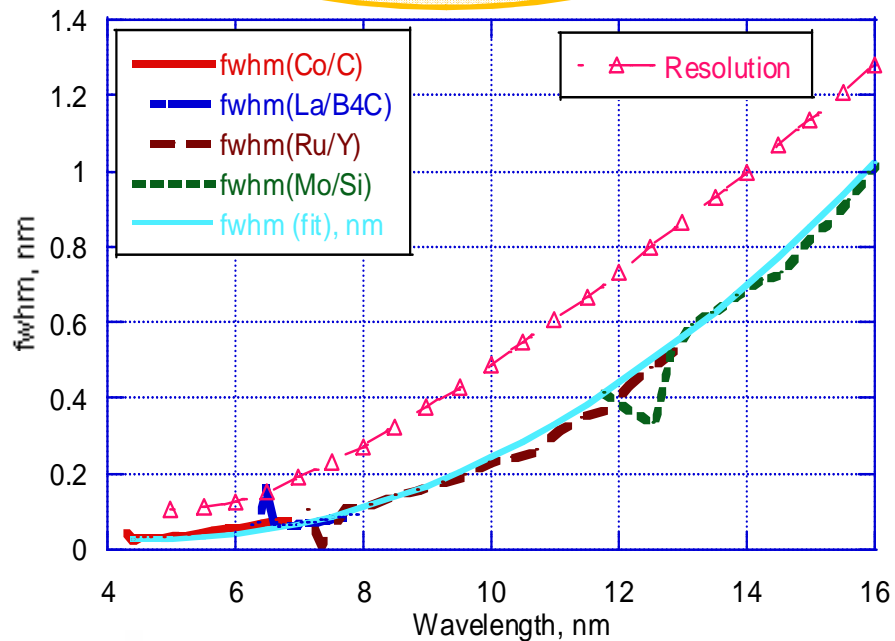
Slide 7 | Public



Maui EUVL Workshop, 14-17 June 2011

# Why 6.X nm: ML reflectivity

Maximum peak reflectivity of multilayers in the wavelength range from 4nm to 16nm is expected to be at **~13.5nm** and **~6.6nm**



$$\Delta\lambda = 0.20523 - 0.075113 \cdot \lambda + 0.0078905 \cdot \lambda^2$$

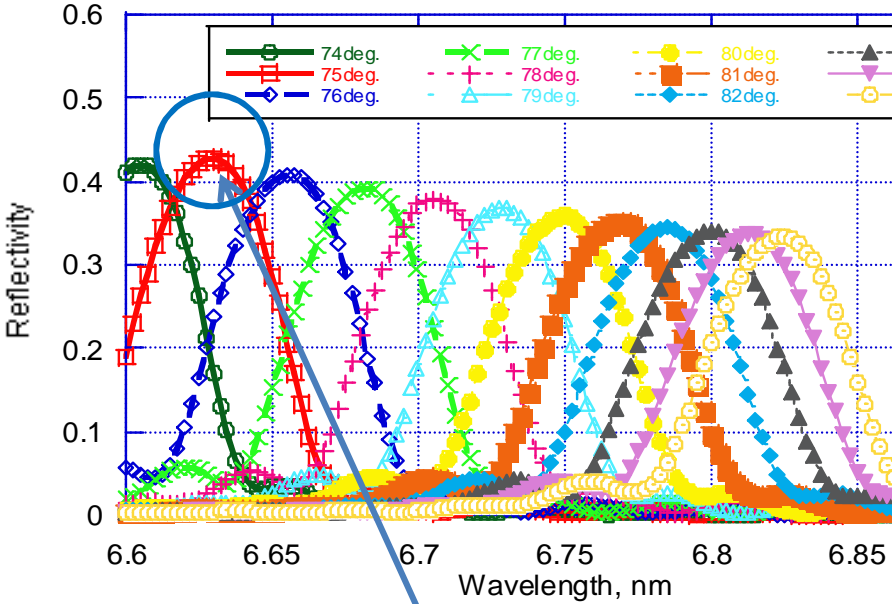
Shorter wavelength



Narrower reflectivity curve

# Wavelength of maximum reflection

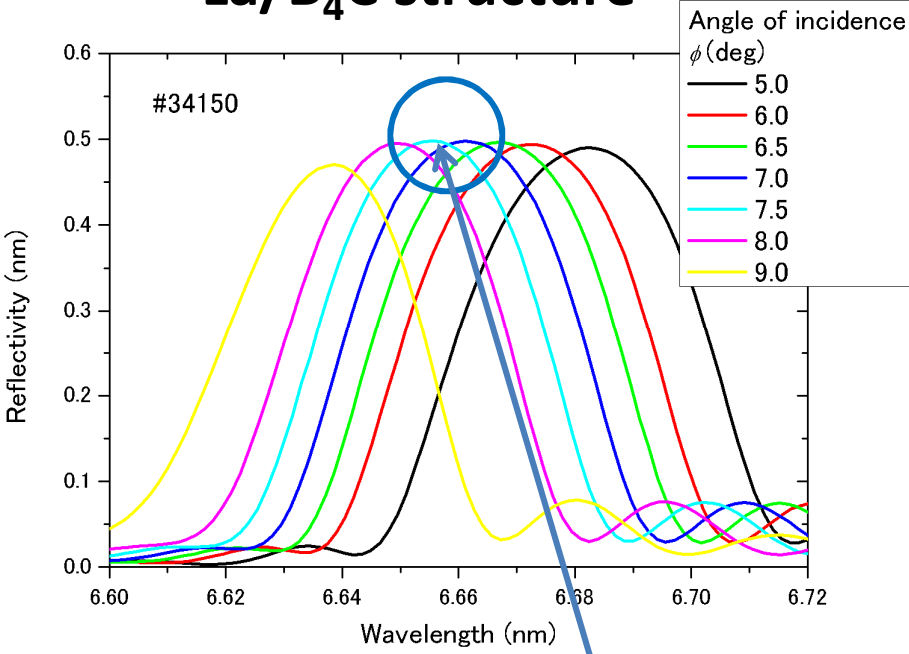
### La<sub>2</sub>O<sub>3</sub>/B<sub>4</sub>C structure



Measurements at CXRO,  
March 2011

**R(max)=42.8% at ~6.63nm**

### La/B<sub>4</sub>C structure



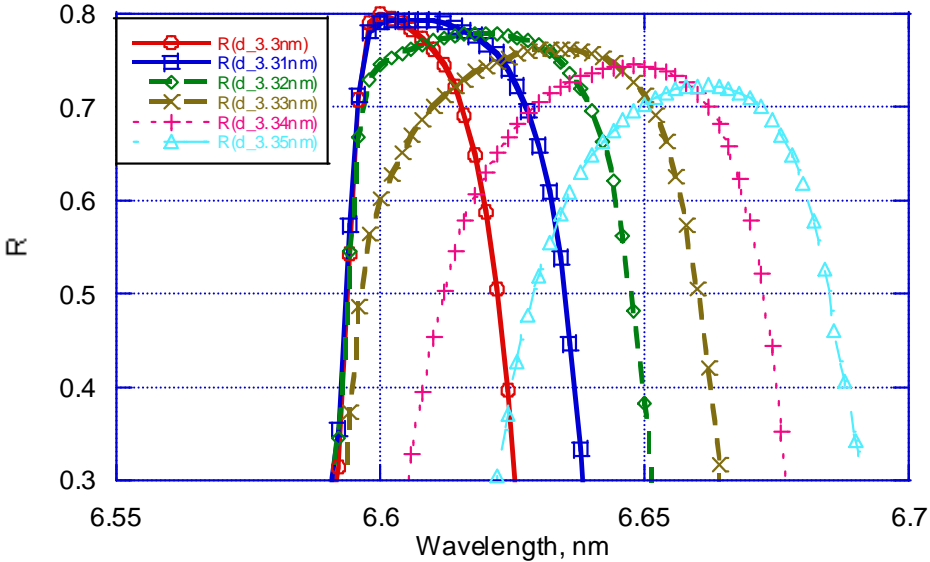
Measurements at New Subaru,  
May, 2011

**R(max)=49.83% at ~6.656nm**

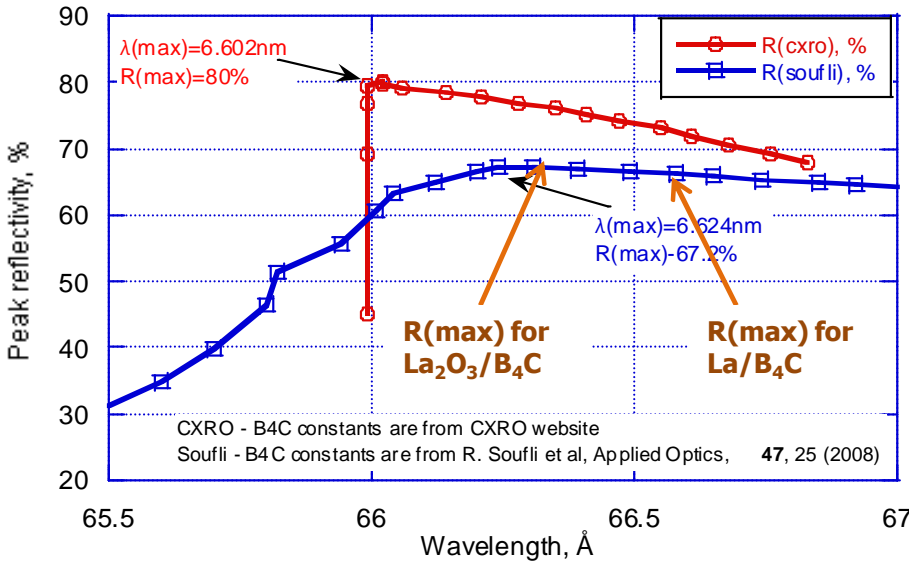


# Optical constants and maximum reflectivity

Performance of La/B4C structures.  
Calculations on CXRO website.



Reflectivity of La/B4C structures versus wavelength  
calculated with two different sets of B4C constants.



# Is today's ML deposition technology ready for HVM?

# MLO Supply Readiness – Pre-HVM (NXE3100-3300)

Application	Coatings	Substrates
Collector Optics	✓	✓
Illumination Optics	✓	✓
Projection Optics	✓	✓
Mask Blank	✓	✓
Metrology Optics	✓	✓

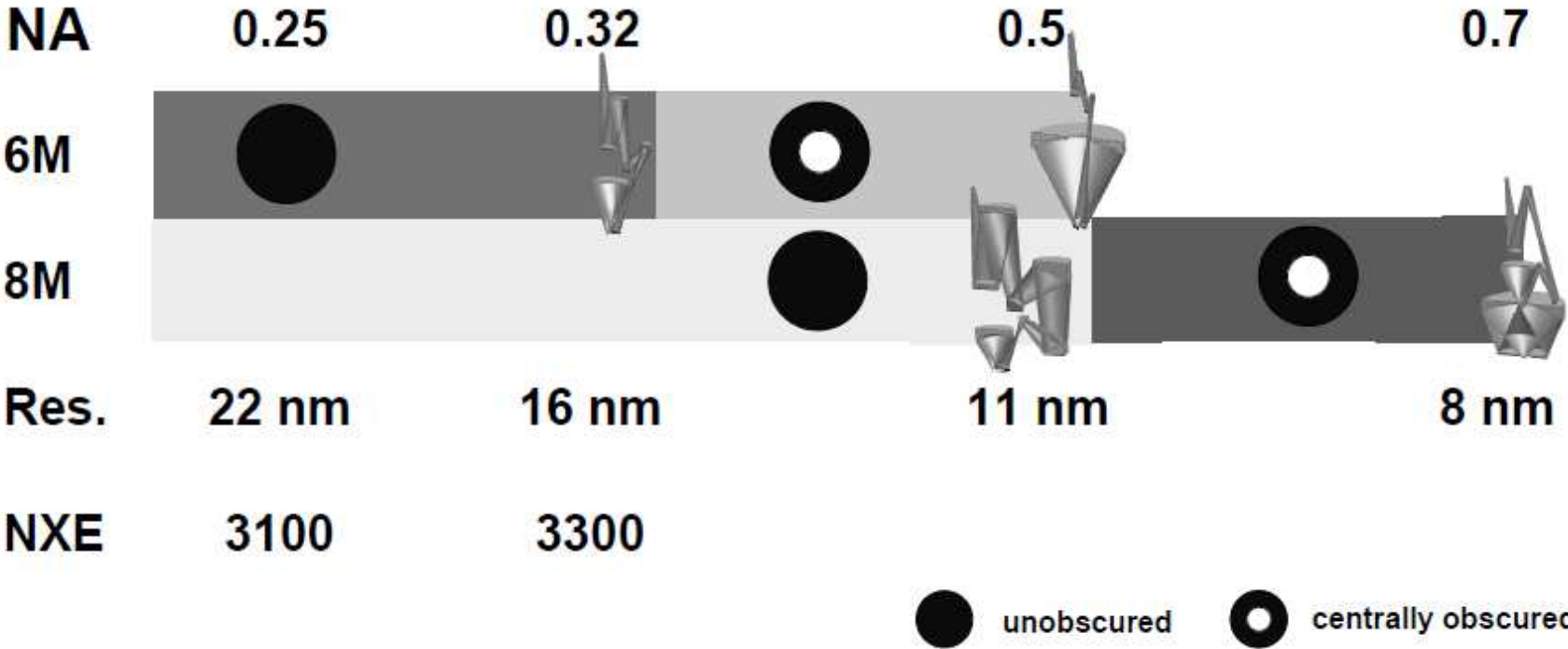
Largely internalized supply (with Institutional support & supply) covers small number of tool shipments; scanners, sources, limited scope for metrology tool development





# Designs for current and future tools

Solution overview:



Extreme Ultraviolet (EUV) Lithography, edited by Bruno M. La Fontaine, Proc. of SPIE Vol. 7636, 763603 · © 2010 SPIE · CCC code: 0277-786X/10/\$18 · doi: 10.1117/12.848624





# Optics: High NA Optics Design

NIKON CORPORATION  
Precision Equipment Company  


$CD = k_1 \lambda / NA$     $DOF = \lambda / NA^2$

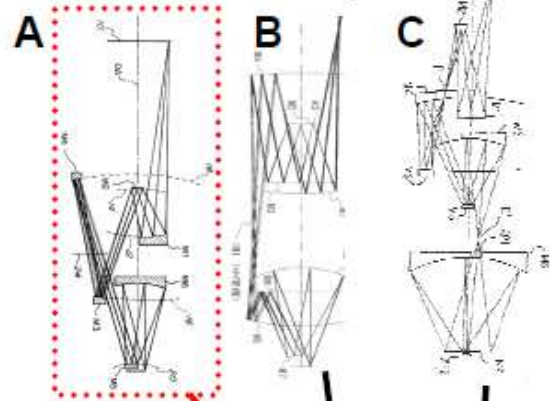
HP	K1					DOF(nm)
	32nm	22nm	16nm	11nm	8nm	
NA0.25	0.59	0.42	0.29	0.21	0.15	216
NA0.30	0.71	0.50	0.35	0.25	0.18	150
NA0.35	0.82	0.58	0.41	0.29	0.21	110
NA0.40	0.94	0.67	0.47	0.33	0.24	84
NA0.45		0.75	0.53	0.38	0.27	67
NA0.50		0.83	0.59	0.42	0.29	54

## General issues:

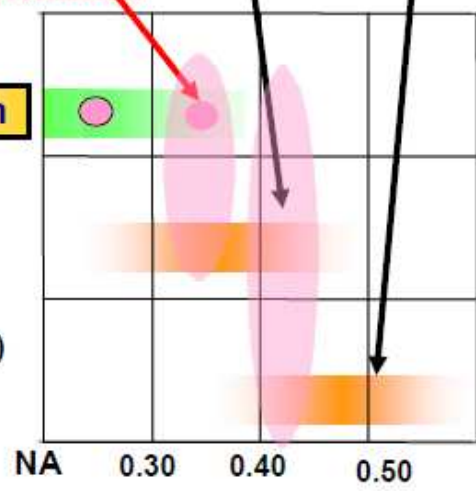
1. DOF reduction
2. Flare increase
3. Transmittance loss
4. Obscuration
5. Manufacturing difficulty

- 6 mirror optics design with NA0.35 achieved.
- Optics design with NA>0.4 being continued.

## Design examples



- A **6 mirror system**
- B 8 mirror system
- C 8 mirror system (center obscuration)



# MLO Supply Readiness – HVM (NXE3500 and beyond, + New Entrants)

Application	Coatings	Substrates
Collector Optics	√ <sup>a)</sup>	√ <sup>a)</sup>
Illumination Optics	√ <sup>b)</sup>	√ <sup>b)</sup>
Projection Optics	√ <sup>b)</sup>	√ <sup>b)</sup>
Mask Blank	√ <sup>c)</sup>	√ <sup>c)</sup>
Metrology Optics	√ <sup>d)</sup>	√ <sup>d)</sup>

- a) What is the required volume in HVM? When needed?
- b) There is no published spec for higher NA optics
- c) There are still added coating defects
- d) There is currently no supplier of metrology tools

# Conclusion

- MLO technology for 13.5 nm is sufficiently developed to support pre-HVM deployment(s). Deposition of higher NA optics for HVM will require further development.
- For the Next Generation EUVL, the choice of light source fuel and multilayer materials is still in R&D feasibility phase.
- The establishment of multilayer optics infrastructure based on proven low volume manufacturing is, in principal extendable and scalable to HVM.

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- IPM – N. Salashchenko, N. Chkhalo

# Thank you



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